

Update : 6/15/2020

This workstation allows you to capture and precisely deposit copper balls (bumps) on printed circuits.



Non contractual Photo

1 - Design

Thanks to Venturi directly linked to the compressed air network, the device can place 250 bumps of diameter between $\varnothing 1$ and $\varnothing 1,6$ mm.

Then, the bumps are placed on the printed circuits which are first coated with a soldering or sintering paste.

Positioning vane for components ensure a repeatability of the bumps drop on the tracks with an accuracy of ± 0.02 mm.

This vane can be soldered at $+250^{\circ}\text{C}$ to ensure the bumps soldering or sintering on the components.

2 - Applications

- Prehension by suction and place of the bumps
- Accurate positioning of objects of small size

3 - Technical Specifications

CHARACTERISTICS (off options)	VALUES
Bumps dimensions	$\varnothing 1$ to $\varnothing 1,6$ mm
PCB dimensions	50 x 40 x 1mm
Accuracy of positioning	$\pm 0,02$ mm
Device dimensions	350 x 300 x 460 mm
Device mass	≤ 8 kg

4 - Options

Preheating kit:

- Removable 2KW air heater on guide rail
- Diffusion chamber
- Temperature sensor
- Programmable temperature control

Additional grid for bumps repartition:

- Bumps repartition on the prehension grid , on request
- Same on the grid layout of the bumps

5 - Dimensions

